

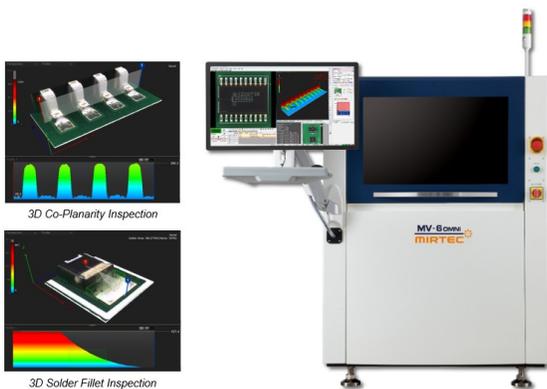


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MIRTEC to Demonstrate the Latest in Their Award-Winning 3D AOI and SPI Systems at SMTAI

August 2019 – MIRTEC, “The Global Leader in Inspection Technology,” announces that it will exhibit in Booth #305 at SMTA International, scheduled to take place Sep. 24-25th, 2019 at the Donald Stephens Convention Center in Rosemont, IL. MIRTEC will showcase the latest advancements in their award-winning 3D AOI and SPI Systems at the two-day event. “We at MIRTEC are very excited to present what are unquestionably the Inspection Industry’s most Technologically Advanced 3D AOI and 3D SPII Systems at SMTAI 2019,” stated Brian D’Amico, President of MIRTEC’s North American Sales and Service Division.



The all new **MV-6 OMNI 3D AOI Machine** combines MIRTEC’s exclusive 15 Mega Pixel CoaXPress Camera Technology with their proprietary OMNI-VISION® 3D Digital Tri-Frequency Moiré Technology to provide precision inspection of SMT devices on finished PCB assemblies.

MIRTEC’s exclusive 15 Mega Pixel CoaXPress Camera System is designed and manufactured by MIRTEC for use with its complete product range of inspection equipment.

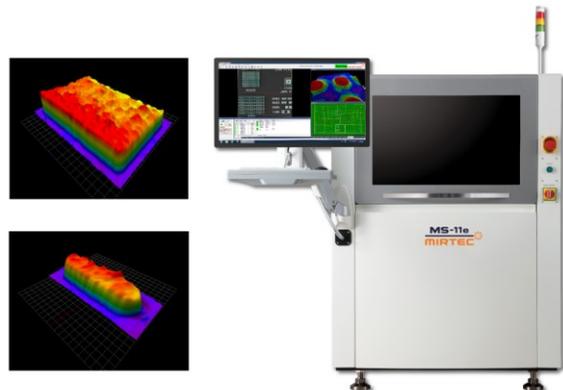
MIRTEC’s proprietary Digital Tri-Frequency Moiré Technology, provides superior 3D inspection of SMT and Thru-Hole devices up to 25mm tall. This industry acclaimed technology yields precise height measurement data used to detect lifted component and lifted lead defects as well as solder volume post reflow. Fully configured

the new MIRTEC MV-6 OMNI machines feature four (4) 10 Mega Pixel Side-View Cameras in addition to the 15 Mega Pixel Top-Down Camera. There is little doubt that this new technology has set the standard by which all other inspection equipment are measured.

MIRTEC’s award-winning **MS-11e 3D SPI Machine** is configured with an exclusive 15 Mega Pixel CoaXPress Camera System, providing enhanced image quality, superior accuracy and incredibly fast inspection rates.

The MS-11e uses Dual Projection Shadow Free Moiré Phase Shift Imaging Technology to inspect solder paste depositions on PCBs post screen print for insufficient solder, excessive solder, shape deformity, shift of deposition and bridging. The MS-11e uses the same robust platform as MIRTEC’s MV-6 OMNI Series.

MIRTEC’s total quality management system software, **INTELLISYS®** also will be on display at SMTA International. This software suite promotes continuous process improvement by allowing manufacturers to track and eliminate defects on inspected assemblies.



“MIRTEC has earned a solid reputation in the Electronics Manufacturing Industry by providing unprecedented performance, quality and cost-effectiveness to the inspection environment,” continued D’Amico. “We look forward to welcoming visitors to our booth during the two-day event.”

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MIRTEC is a leading global supplier of automated inspection systems to the electronics manufacturing industry. For further information, please visit www.mirtec.com